



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC0923NDI		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001013780						
<b>Package</b>		PG-TISON-8-2		<b>Weight*</b>		96.80 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.785	0.81	0.81	8111	8111
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		106	
	non noble metal	zinc	7440-66-6	0.041	0.04		424	
	non noble metal	iron	7439-89-6	0.822	0.85		8487	
wire	non noble metal	copper	7440-50-8	33.360	34.46	35.36	344627	353644
	noble metal	gold	7440-57-5	0.061	0.06	0.06	635	635
encapsulation	organic material	carbon black	1333-86-4	0.095	0.10		983	
	plastics	epoxy resin	-	4.899	5.06		50612	
	inorganic material	silicondioxide	60676-86-0	42.571	43.99	49.15	439779	491374
leadfinish	non noble metal	tin	7440-31-5	1.122	1.16	1.16	11589	11589
plating	noble metal	silver	7440-22-4	0.186	0.19	0.19	1919	1919
solder	noble metal	silver	7440-22-4	0.031	0.03		320	
	non noble metal	tin	7440-31-5	0.025	0.03		256	
	non noble metal	lead	7439-92-1	1.185	1.22	1.28	12239	12815
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003	0.00		36	
	non noble metal	zinc	7440-66-6	0.014	0.01		144	
	non noble metal	iron	7439-89-6	0.279	0.29		2878	
	non noble metal	copper	7440-50-8	11.312	11.69	11.99	116855	119913
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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